



# APPROVAL SHEET

| Approval Specification   | Customer's Approval Certificate   |
|--|---|
| <p><b>TO:</b></p> <p><b>Part No.:</b></p> <p><b>Customer's Part No.:</b></p> | <p>Please return this copy as a certification of your approval</p> <p><b>Checked &amp; Approved by:</b></p> <p><b>Date:</b></p> |

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|          |   |           |
|----------|---|-----------|
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|                     |    |
|---------------------|----|
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| <b>Checked by:</b>  |    |
| <b>Approved by:</b> |    |

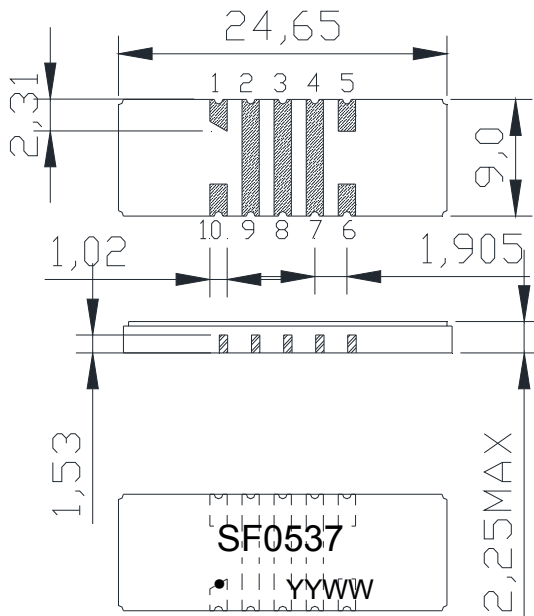
**Application**

- Low -loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 2.2 MHz

**Features**

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 24.65x9.00x2.25mm<sup>3</sup>
- Package Code SMD24
- **Electrostatic Sensitive Device(ESD)**

**Package Dimensions (Unit: mm)**



**Pin Configuration**

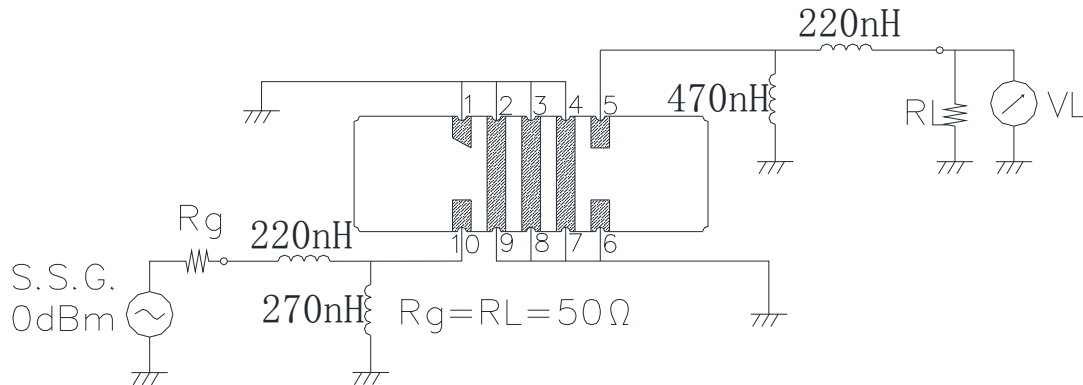
| Pin No.         | Description |
|-----------------|-------------|
| 10              | Input       |
| 5               | Output      |
| 1,2,3,4,6,7,8,9 | Ground      |

**Marking Description**

|             |                       |
|-------------|-----------------------|
| <b>S</b>    | Trademark             |
| <b>F</b>    | SAW Filter            |
| <b>0537</b> | Part Number           |
| ●           | Pin 1                 |
| <b>YYWW</b> | Year Code & Week Code |

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Test Circuit(Bottom View)**



**Performance****Maximum Rating**

| Item                  |                  | Value      | Unit |
|-----------------------|------------------|------------|------|
| DC Voltage            | V <sub>DC</sub>  | 3          | V    |
| Operation Temperature | T                | -40 ~ +85  | °C   |
| Storage Temperature   | T <sub>stg</sub> | -55 ~ +125 | °C   |
| RF Power Dissipation  | P                | 10         | dBm  |

**Electronic Characteristics**

Test Temperature: 25°C ± 2°C

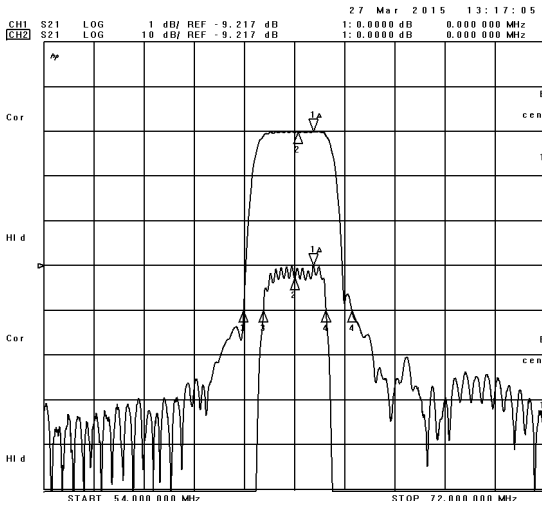
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

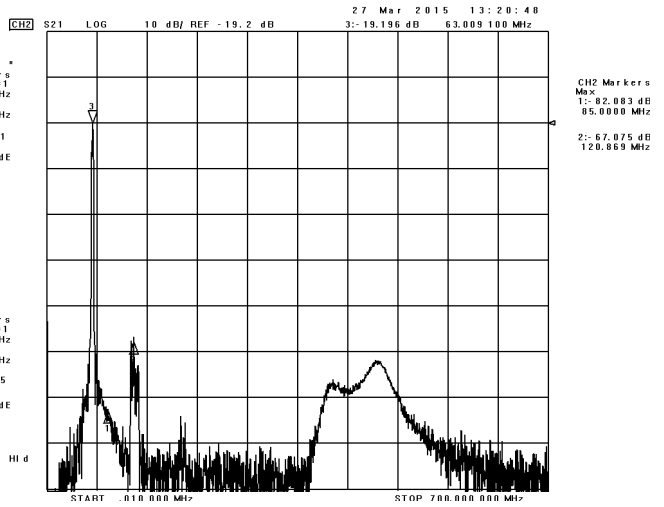
| Item                              |                   | Minimum | Typical | Maximum | Unit |
|-----------------------------------|-------------------|---------|---------|---------|------|
| Center Frequency                  | f <sub>c</sub>    |         | 63.00   |         | MHz  |
| Insertion Loss(min)               | IL                |         | 9.30    | 11.0    | dB   |
| 1 dB Bandwidth                    | BW <sub>1dB</sub> | 2.20    | 2.25    | 2.40    | MHz  |
| Phase Linearity<br>61.90-64.10MHz |                   |         | 7.0     | 8.0     | deg  |
| Absolute Attenuation              | α                 |         |         |         |      |
|                                   | 61.10MHz          | 35.0    | 40.0    |         | dB   |
|                                   | 64.90MHz          | 35.0    | 36.0    |         | dB   |
|                                   | 85.00MHz          | 50.0    | 58.0    |         | dB   |
|                                   | 85.00-700.00MHz   | 40.0    | 43.0    |         | dB   |

Frequency Characteristics

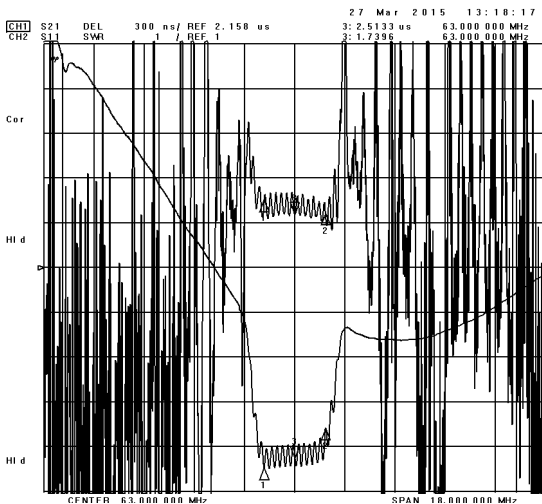
Frequency Response



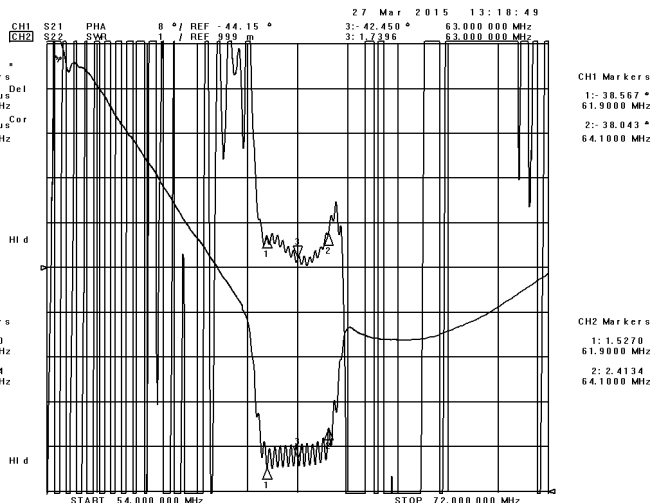
Frequency Response (wideband)



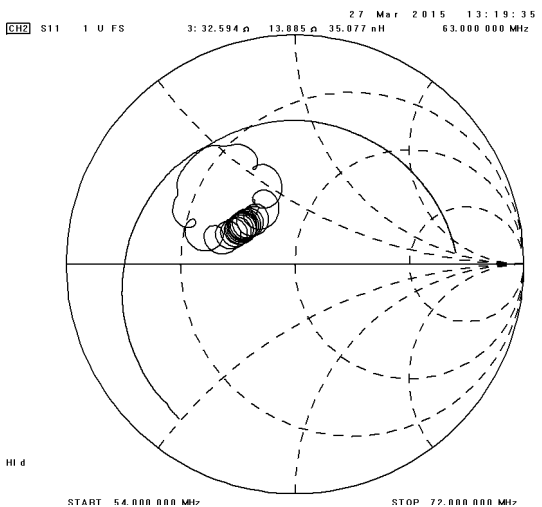
Delay Ripple & S11 VSWR



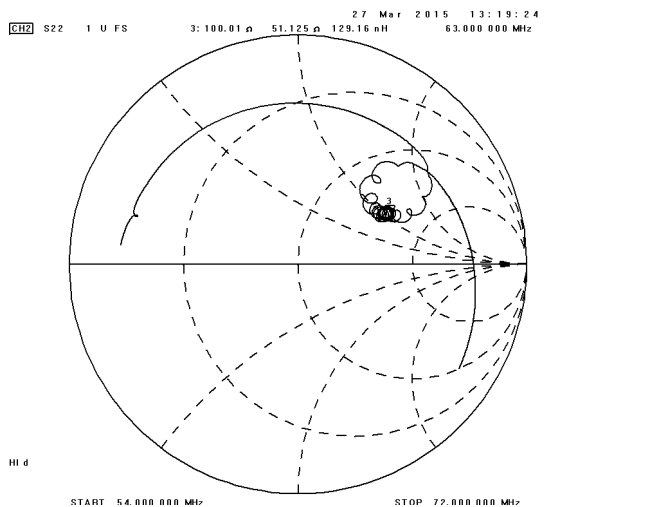
Phase Linearity & S22 VSWR



S11 Smith Chart



S22 Smith Chart





**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.